

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
▼	323	10.00mil <0.254mm>	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
⊗	16	43.31mil <1.100mm>	PTH	Round	Top Layer - Bottom Layer	Pad	<Mixed>
	339 Total						

NOTES: UNLESS OTHERWISE SPECIFIED.

1. FABRICATE PER IPC-6012A CLASS 2.

2. MATERIAL:

DIELECTRIC: FR4 PER IPC-4101 WITH MIN TG 180 DEGREE C.

COPPER: AS PER STACKUP.

U.L. RATING: 94V-0 MINIMUM

3. SURFACE FINISH: ENIG

4. SOLDER MASK ON BOTH SIDES OF THE BOARD SHALL BE IPC-SM-840C AND GREEN IN COLOR AND APPLIED BARE COPPER.

5. SILK SCREEN LEGEND TO BE APPLIED PER LAYER STACKUP USING WHITE NON-CONDUCTIVE EPOXY INK.

6. 100% CONTINUITY TESTING USING DATABASE NETLIST SHALL BE PERFORMED, VENDOR TO IDENTIFY TEST PASSED IN SECONDARY SIDE.

7. VENDOR TO MAKE DATE CODE AND LOGO IN EACH OR IN LEGEND.

8. BOW AND TWIST SHALL NOT EXCEED 0.7% OF LONGEST SIDE.

9. DIELECTRICS AND LINEWIDTHS MAY BE ADJUSTED TO MEET THE IMPEDANCE.

10. MINIMUM CONDUCTOR WIDTH: 6 MMIL

MINIMUM SPACING: 3.4 MIN.

11. REQUEST FABRICATOR TO ADD TEAR DROPS IF NOT ADDED IN THE GERBER

12. AUTOMATIC INSPECTION OF ALL LAYERS REQUIRED.

13. NUMBER OF LAYERS IS 6

14. BOARD THICKNESS IS 1.6MM

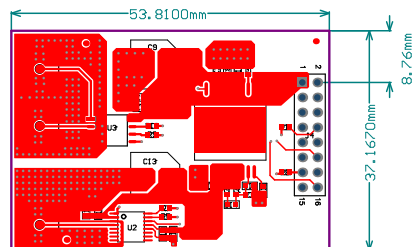
15. REQUEST FABRICATOR TO ADD TEAR DROPS IF NOT ADDED IN GERBER.

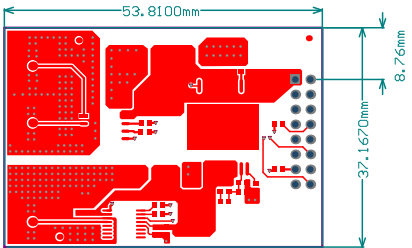
16. AUTOMATIC INSPECTION OF ALL LAYERS REQUIRED.

17. NUMBER OF LAYERS IS 4.

18. ALL VIAS ARE TENTED ON BOTH SIDES UNLESS SOLDER MASK OPENED IN GERBER.

19. BOARD THICKNESS IS 1.6MM.





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